

## N-Channel 60V(D-S) MOSFET

Product summary		
V <sub>DS</sub>	60	V
R <sub>DS(ON)</sub> (at V <sub>GS</sub> =4.5V) Typ.	1.9	Ω
R <sub>DS(ON)</sub> (at V <sub>GS</sub> =2.5V) Typ.	2.3	Ω
I <sub>D</sub> (T <sub>A</sub> =25°C)	0.2	A

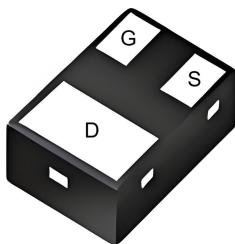
### Features

- Advanced Trench Technology
- ESD protection :1.5 kV
- Small package DFN1006-3L

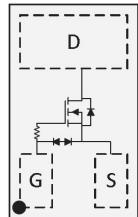
### Applications

- Battery Operated System
- Solid-State Relays

### Pin Configuration



DFN1006-3L



### Packing Information

Device	Package	Reel Size	Quantity(Min. Package)
ECAD138K	DFN1006-3L	7"	10000pcs

### Absolute Maximum Ratings (at T<sub>A</sub>=25°C Unless Otherwise Noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	60	V
V <sub>GS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current <sup>AC</sup>	T <sub>A</sub> =25°C	A
		T <sub>A</sub> =70°C	A
I <sub>DM</sub>	Pulse Drain Current Tested <sup>B</sup>	0.8	A
P <sub>D</sub>	Power Dissipation <sup>AC</sup>	T <sub>A</sub> =25°C	W
T <sub>J,STG</sub>	Junction and Storage Temperature Range	-55 to +150	°C

### Thermal Characteristics

Symbol	Parameter	Typical	Units
R <sub>θJA</sub>	Thermal Resistance-Junction to ambient <sup>A</sup>	416	°C/W

## Electrical Characteristics (at $T_J = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
<b>Static Parameters</b>						
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	60	--	--	V
$I_{\text{DSS}}$	Zero Gate Voltage Drain Current	$V_{\text{DS}}=60\text{V}, V_{\text{GS}}=0\text{V}$	--	--	1	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Body Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	--	--	$\pm 10$	$\mu\text{A}$
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	0.5	0.9	1.3	V
$R_{\text{DS(ON)}}$	Drain-Source On-State Resistance <sup>D</sup>	$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=0.3\text{A}$	--	1.9	2.5	$\Omega$
		$V_{\text{GS}}=2.5\text{V}, I_{\text{D}}=0.2\text{A}$	--	2.3	4.5	$\Omega$
$V_{\text{SD}}$	Forward Voltage	$I_{\text{SD}}=0.3\text{A}, V_{\text{GS}}=0\text{V}$	--	--	1.2	V
<b>Dynamic Parameters E</b>						
$C_{\text{iss}}$	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=25\text{V}$ $f=1\text{MHZ}$	--	22	--	pF
$C_{\text{oss}}$	Output Capacitance		--	3	--	pF
$C_{\text{rss}}$	Reverse Transfer Capacitance		--	2	--	pF
$Q_g$	Total Gate Charge	$V_{\text{DS}}=10\text{V}, I_{\text{D}}=0.3\text{A}$ $V_{\text{GS}}=4.5\text{V}$	--	1.8	--	nC
$Q_{\text{gs}}$	Gate-Source Charge		--	0.4	--	nC
$Q_{\text{gd}}$	Gate-Drain Charge		--	0.7	--	nC
$t_{\text{D(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=10\text{V}$ $I_{\text{D}}=0.2\text{A},$ $V_{\text{GS}}=10\text{V}, R_{\text{GEN}}=10\Omega$	--	2	--	ns
$t_r$	Turn-on Rise Time		--	16	--	ns
$t_{\text{D(off)}}$	Turn-off Delay Time		--	7	--	ns
$t_f$	Turn-off Fall Time		--	19	--	ns

A. The data tested by surface mounted on a 1 inch x 1 inch FR-4 board with 2OZ copper.

B. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

C. Maximum junction temperature  $T_J=150^\circ\text{C}$ .

D. Pulse Test: Pulse Width  $\leq 300\text{us}$ , Duty cycle  $\leq 2\%$ .

E. Guaranteed by design, not subject to production testing.

## Test Circuit

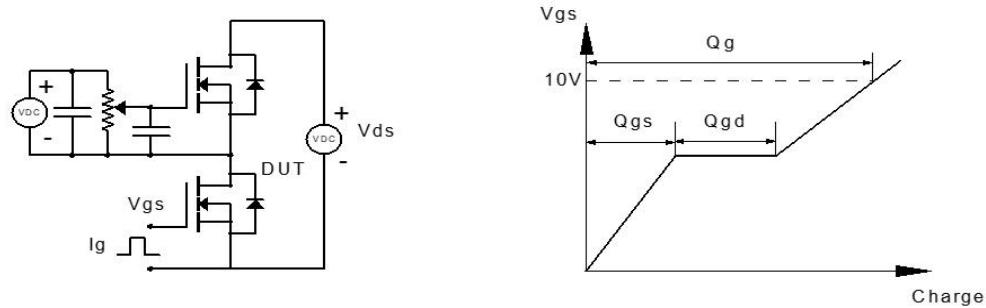


Figure 1: Gate Charge Test Circuit &amp; Waveform

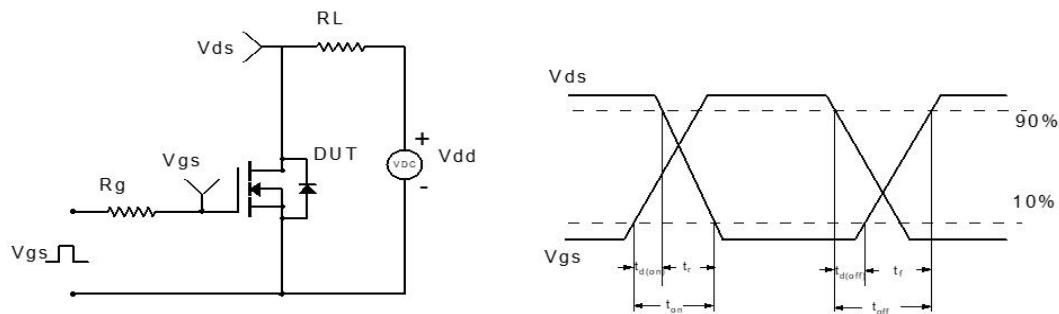


Figure 2: Resistive Switching Test Circuit &amp; Waveform

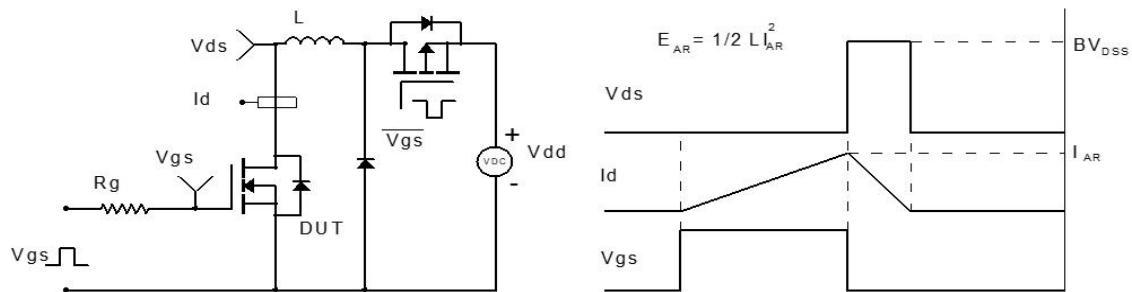


Figure 3: Unclamped Inductive Switching Test Circuit &amp; Waveform

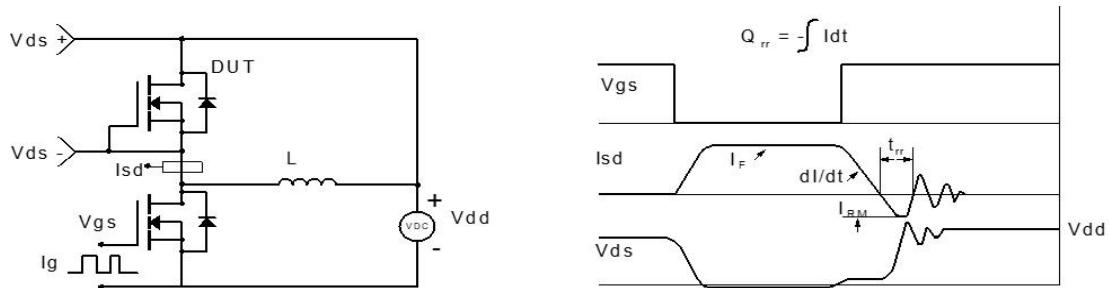
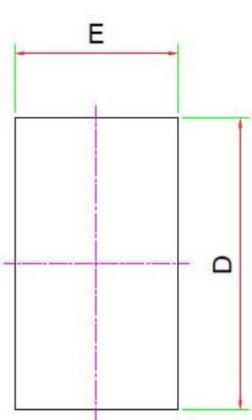
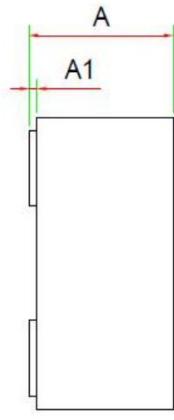


Figure 4: Diode Recovery Test Circuit &amp; Waveform

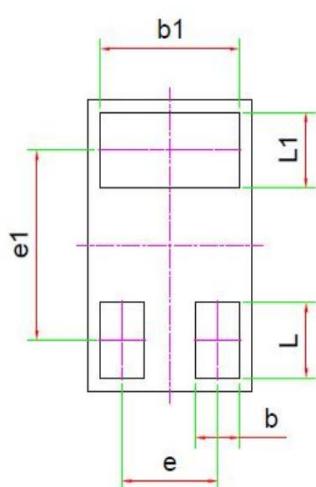
## DFN1006-3L Package Information



TOP VIEW



SIDE VIEW



BOTTOM VIEW

SYMBOL	MIN	NOM	MAX
A	0.45	0.50	0.55
A1	0.00	NA	0.03
L	0.22	0.26	0.30
b	0.12	0.16	0.20
D	0.95	1.00	1.05
E	0.55	0.60	0.65
L1	0.22	0.26	0.30
b1	0.47	0.51	0.55
e		0.35 BSC	
e1		0.65 BSC	